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30 July 2003



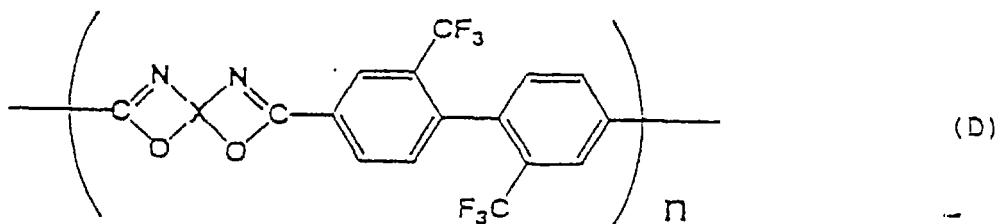
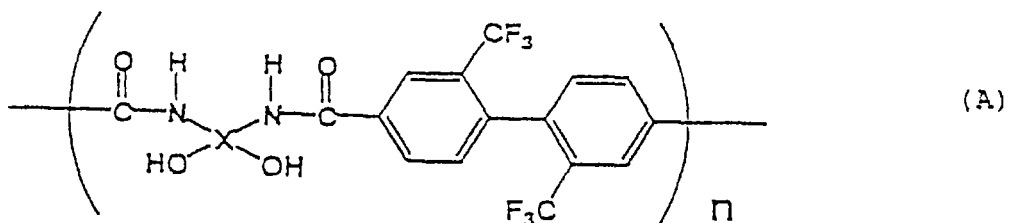
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- 17 -

Abstract

POLYBENZOXAZOLE RESIN AND PRECURSOR THEREOF

The present invention provides heat resistant resins excellent in all of thermal characteristics, electrical characteristics, physical characteristics and mechanical characteristics in use for semiconductors. That is, the present invention provides polybenzoxazole precursors represented by the following general formula (A) and polybenzoxazole resins represented by the following general formula (D).



In the above formulas (A) and (D), n denotes an integer of 2-1000 and X denotes a tetravalent aromatic group as defined in the specification.